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LM2840/LM2841/LM2842/ LM2840Q/LM2841Q/ LM2842Q

100/300/600 mA Input Step-Down DC/DC Regulator in Thin **SOT-23**

General Description

The LM2840, LM2841 and LM2842 are PWM DC/DC buck (step-down) regulators. With a wide input range from 4.5V-42V, they are suitable for a wide range of applications such as power conditioning from unregulated sources. They feature a low ${\rm R}_{\rm DSON}$ (0.9 Ω typical) internal switch for maximum efficiency (85% typical). Operating frequency is fixed at 550 kHz (X version) and 1.25 MHz (Y version) allowing the use of small external components while still being able to have low output voltage ripple. Soft-start can be implemented using the shutdown pin with an external RC circuit allowing the user to tailor the soft-start time to a specific application.

The LM2840 is optimized for up to 100 mA, the LM2841 for 300 mA and the LM2842 is optimized for up to 600 mA load currents. They all have a 0.765V nominal feedback voltage.

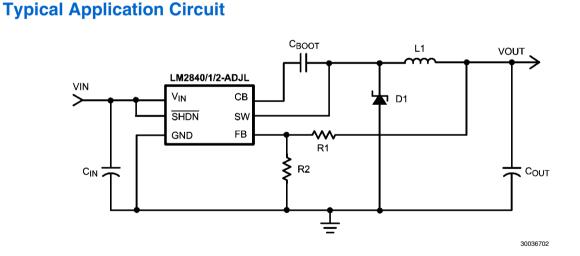
Additional features include: thermal shutdown, V_{IN} under-voltage lockout, and gate drive under-voltage lockout. The LM2840, LM2841 and LM2842 are available in a low profile TSOT-6L package.

Features

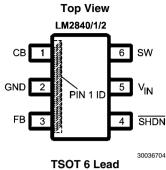
- LM2840Q, LM2841Q and LM2842Q are Automotive Grade products that are AEC-Q100 grade 1 gualified (-40° C to +125°C operating junction temperature)
- Input voltage range of 4.5V to 42V
- Output current options of 100 mA, 300 mA and 600 mA
- Feedback pin voltage of 0.765V
- 550 kHz (X) or 1.25 MHz (Y) switching frequency
- Low shutdown Io, 16 µA typical
- Short circuit protected
- Internally compensated
- Soft-start circuitry
- Small overall solution size (TSOT-6L package) .

Applications

- Battery powered equipment
- Industrial distributed power applications
- Portable media players
- Portable hand held instruments



Connection Diagram



NS Package Number MK06A

Ordering Information

Order Number	Spec.	Package Type	NSC Package Drawing	Top Mark	Supplied As	Feature
LM2840XMK-ADJL				SE8B	1000 Units, Tape and Reel	
LM2840XMKX-ADJL					3000 Units, Tape and Reel	
LM2840YMK-ADJL				SF1B	1000 Units, Tape and Reel	
LM2840YMKX-ADJL				SFID	3000 Units, Tape and Reel	
LM2841XMK-ADJL				STFB	1000 Units, Tape and Reel	
LM2841XMKX-ADJL				SIFD	3000 Units, Tape and Reel	
LM2841YMK-ADJL]			STTB	1000 Units, Tape and Reel	
LM2841YMKX-ADJL				SIIB	3000 Units, Tape and Reel	
LM2842XMK-ADJL				STVB	1000 Units, Tape and Reel	
LM2842XMKX-ADJL				SIVB	3000 Units, Tape and Reel	
LM2842YMK-ADJL				STXB	1000 Units, Tape and Reel	
LM2842YMKX-ADJL		MIKOGA	• · · · -	3000 Units, Tape and Reel		
LM2840XQMK	NOPB	TSOT-6	MK06A	SE9B	1000 Units, Tape and Reel	
LM2840XQMKX				2EAR	3000 Units, Tape and Reel	AEC-Q100 Grade 1 qualified. Automotive Grade Production
LM2840YQMK				SF2B	1000 Units, Tape and Reel	
LM2840YQMKX					3000 Units, Tape and Reel	
LM2841XQMK				SB1B SB2B	1000 Units, Tape and Reel	
LM2841XQMKX					3000 Units, Tape and Reel	
LM2841YQMK					1000 Units, Tape and Reel	
LM2841YQMKX					3000 Units, Tape and Reel	Flow*
LM2842XQMK				0000	1000 Units, Tape and Reel	
LM2842XQMKX				SB3B	3000 Units, Tape and Reel	
LM2842YQMK	1			SB4B	1000 Units, Tape and Reel	
LM2842YQMKX				5B4B	3000 Units, Tape and Reel	

*Automotive Grade (Q) product incorporates enhanced manufacturing and support processes for the automotive market, including defect detection methodologies. Reliability qualification is compliant with the requirements and temperature grades defined in the AEC-Q100 standard. Automotive grade products are identified with the letter Q. For more information go to http://www.national.com/automotive.

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340Q/LM284
340Q/LM284
340Q/LM2841
340Q/LM28410
340Q/LM2841Q
340Q/LM2841Q/
340Q/LM2841Q/L
340Q/LM2841Q/L
340Q/LM2841Q/LN
340Q/LM2841Q/LM
340Q/LM2841Q/LM2
340Q/LM2841Q/LM28
340Q/LM2841Q/LM28
340Q/LM2841Q/LM284
340Q/LM2841Q/LM2842
340Q/LM2841Q/LM2842
340Q/LM2841Q/LM28420
M2841Q/LM284

Pin Descriptions

Pin Name		Function		
1	СВ	SW FET gate bias voltage. Connect C _{BOOT} cap between CB and SW.		
2	GND	Ground connection.		
3	FB	Feedback pin: Set feedback voltage divider ratio with $V_{OUT} = V_{FB} (1+(R1/R2))$. Resistors should be in the 100-10K range to avoid input bias errors.		
4	SHDN	Logic level shutdown input. Pull to GND to disable the device and pull high to enable the device If this function is not used tie to V_{IN} or leave open.		
5	V _{IN}	Power input voltage pin: 4.5V to 42V normal operating range.		
6	SW	Power FET output: Connect to inductor, diode, and C _{BOOT} cap.		

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

V _{IN}	-0.3V to +45V
SHDN	-0.3V to (V _{IN} +0.3V)
	SHDN=V _{IN} at 45V max
SW Voltage	-0.3V to +45V
CB Voltage above SW Voltage	7V
FB Voltage	-0.3V to +5V
Maximum Junction	150°C
Temperature	
Power Dissipation(<i>Note 2</i>)	Internally Limited

Lead Temperature	300°C
Vapor Phase (60 sec.)	215°C
Infrared (15 sec.)	220°C
ESD Susceptibility	
(<i>Note 3</i>)	
Human Body Model	2 kV

Operating Conditions

Operating Junction	
Temperature Range (<i>Note 4</i>)	–40°C to +125°C
Storage Temperature	–65°C to +150°C
Input Voltage V _{IN}	4.5V to 42V
SW Voltage	Up to 42V

Electrical Characteristics

Specifications in standard type face are for $T_J = 25^{\circ}C$ and those with **boldface type** apply over the full **Operating Temperature Range** ($T_J = -40^{\circ}C$ to $+125^{\circ}C$). Minimum and Maximum limits are guaranteed through test, design, or statistical correlation. Typical values represent the most likely parametric norm at $T_J = +25^{\circ}C$, and are provided for reference purposes only. Unless otherwise stated the following conditions apply: $V_{IN} = 12V$.

I _Q R _{DSON} I _{LSW} I _{CL}	Quiescent current Switch ON resistance Switch leakage current Switch current limit	SHDN = 0V Device On, Not Switching Device On, No Load (Note 6) V _{IN} = 42V		16 1.30	40 1.75	μA
I _{LSW}	Switch leakage current	Device On, No Load (<i>Note 6</i>)			1.75	
I _{LSW}	Switch leakage current	(Note 6)			-	
I _{LSW}	Switch leakage current			1.35	1.85	mA
I _{LSW}	-	$V_{\rm ev} = 42 V$		0.9	1.6	Ω
	Switch current limit			0.0	0.5	μA
		LM2840 (<i>Note 7</i>)		525	900	mA
		LM2841 (<i>Note 7</i>)		525	900	mA
		LM2842 (<i>Note 7</i>)		1.15	1.7	А
I _{FB}	Feedback pin bias current	LM2840/41/42 (Note 8)		0.1	1.0	μA
V _{FB}	FB Pin reference voltage		0.747	0.765	0.782	V
t _{ON(min)}	Minimum ON time	(Note 10)		100	150	ns
t _{OFF(min)}	Minimum OFF time	X option		110	370	ns
()		Y option		104	200	ns
sw		LM2840/41/42X, V _{FB} = 0.5V	325	550	750	
	Switching frequency	LM2840/41/42X, V _{FB} = 0V		140		kHz
		LM2840/41/42Y, V _{FB} = 0.5V	0.95	1.25	1.50	
		LM2840/41/42Y, V _{FB} = 0V		0.35		MHz
D _{MAX}	Maximum duty cycle	LM2840/41/42X	88	94		
		LM2840/41/42Y	81	87		%
V _{UVP}	Undervoltage lockout	On threshold	4.4	3.7		
	thresholds	Off threshold		3.5	3.25	V
V _{SHDN}	Shutdown threshold	Device on	2.3	1.0		V
		Device off		0.9	0.3	v
SHDN	Shutdown pin input bias current	V _{SHDN} = 2.3V (<i>Note 8</i>)		0.05	1.5	
		$V_{\overline{SHDN}} = 0V$		0.02	1.5	μA
THERMAL S	PECIFICATIONS					
R _{eja}	Junction-to-Ambient Thermal	(Note 9)		121		°C/W
	Resistance, TSOT-6L Package			121		0, 11
R _{eJC}	Junction-to-Case Thermal Resistance, TSOT-6L Package			94		°C/W

Note 1: Absolute maximum ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions for which the device is intended to be functional, but device parameter specifications may not be guaranteed. For guaranteed specifications and test conditions, see the Electrical Characteristics.

Note 2: The maximum allowable power dissipation is a function of the maximum junction temperature, $T_J(MAX)$, the junction-to-ambient thermal resistance, θ_{JA} , and the ambient temperature, T_A . The maximum allowable power dissipation at any ambient temperature is calculated using: $P_D (MAX) = (T_{J(MAX)} - T_A)/\theta_{JA}$. Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage. Thermal shutdown engages at $T_J=175^{\circ}C$ (typ.) and disengages at $T_J=155^{\circ}C$ (typ).

Note 3: Human Body Model, applicable std. JESD22-A114-C.

Note 4: All limits guaranteed at room temperature (standard typeface) and at temperature extremes (bold typeface). All room temperature limits are 100% production tested. All limits at temperature extremes are guaranteed via correlation using standard Statistical Quality Control (SQC) methods. All limits are used to calculate Average Outgoing Quality Level (AOQL).

Note 5: Typical numbers are at 25°C and represent the most likely norm.

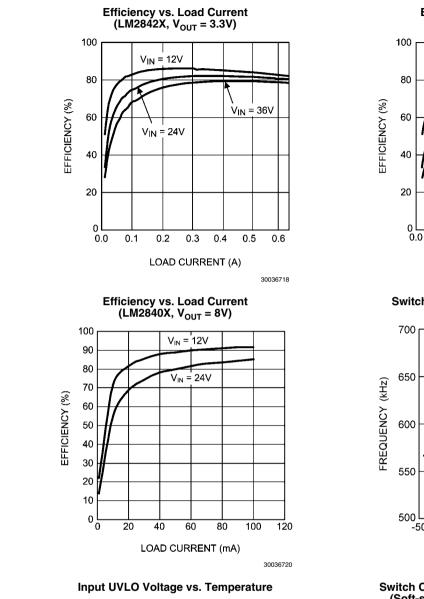
Note 6: Includes the bond wires, R_{DSON} from V_{IN} pin to SW pin.

Note 7: Current limit at 0% duty cycle. May be lower at higher duty cycle or input voltages below 6V.

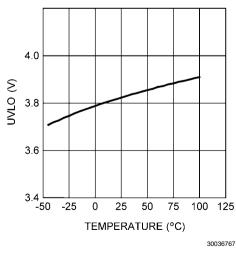
Note 8: Bias currents flow into pin.

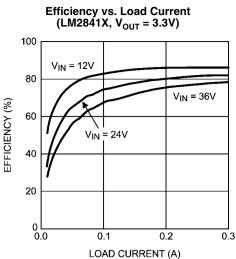
Note 9: All numbers apply for packages soldered directly onto a 3" x 3" PC board with 2 oz. copper on 4 layers in still air in accordance to JEDEC standards. Thermal resistance varies greatly with layout, copper thickness, number of layers in PCB, power distribution, number of thermal vias, board size, ambient temperature, and air flow.

Note 10: Minimum On Time guaranteed by design and simulation.



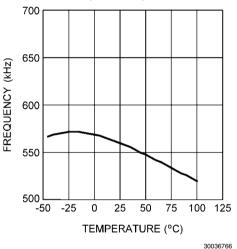
Typical Performance Characteristics



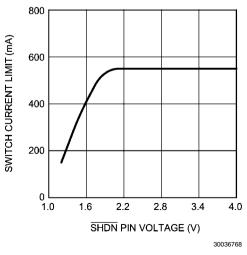


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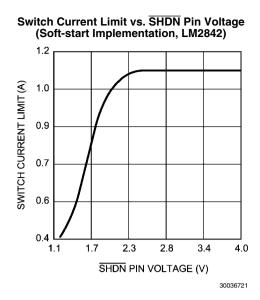
Switching Frequency vs. Temperature (X version)



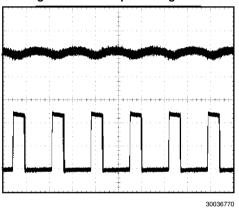
Switch Current Limit vs. SHDN Pin Voltage (Soft-start Implementation, LM2840/41)



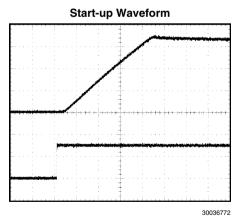
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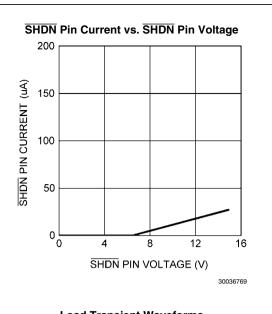
Switching Node and Output Voltage Waveforms

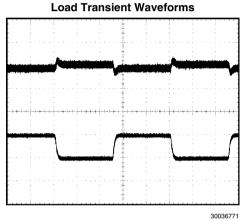


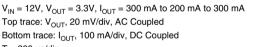
$$\begin{split} V_{IN} &= 12V, \ V_{OUT} = 3.3V, \ I_{OUT} = 200 \ \text{mA} \\ \text{Top trace:} \ V_{OUT}, \ 10 \ \text{mV/div}, \ \text{AC} \ \text{Coupled} \\ \text{Bottom trace:} \ \text{SW}, \ 5V/\text{div}, \ \text{DC} \ \text{Coupled} \\ \text{T} &= 1 \ \mu\text{s/div} \end{split}$$



 $\begin{array}{l} V_{IN} = 12V, \, V_{OUT} = 3.3V, \, I_{OUT} = 50 \, \text{ mA} \\ \text{Top trace: } V_{OUT}, \, 1V/div, \, DC \, Coupled \\ \text{Bottom trace: } \overline{SHDN}, \, 2V/div, \, DC \, Coupled \\ \text{T} = 40 \, \mu s/div \end{array}$

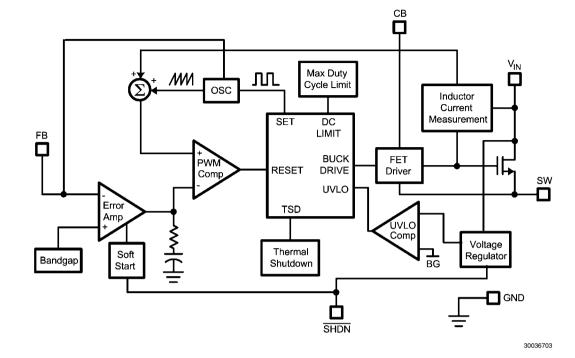






T = 200 µs/div

Block Diagram



Operation

PROTECTION

The LM2840/1/2 has dedicated protection circuitry running during normal operation to protect the IC. The thermal shutdown circuitry turns off the power device when the die temperature reaches excessive levels. The UVLO comparator protects the power device during supply power startup and shutdown to prevent operation at voltages less than the minimum input voltage. A gate drive (CB) under-voltage lockout is included to guarantee that there is enough gate drive voltage to drive the MOSFET before the device tries to start switching. The LM2840/1/2 also features a shutdown mode decreasing the supply current to approximately 16 µA.

CONTINUOUS CONDUCTION MODE

The LM2840/1/2 contains a current-mode, PWM buck regulator. A buck regulator steps the input voltage down to a lower output voltage. In continuous conduction mode (when the inductor current never reaches zero at steady state), the buck regulator operates in two cycles. The power switch is connected between V_{IN} and SW. In the first cycle of operation the transistor is closed and the diode is reverse biased. Energy is collected in the inductor and the load current is supplied by C_{OUT} and the rising current through the inductor. During the second cycle the transistor is open and the diode is forward biased due to the fact that the inductor current cannot instantaneously change direction. The energy stored in the inductor is transferred to the load and output capacitor. The ratio of these two cycles determines the output voltage. The output voltage is defined approximately as: $D=V_{OUT}/V_{IN}$ and D' = (1-D) where D is the duty cycle of the switch. D and D' will be required for design calculations.

DESIGN PROCEDURE

This section presents guidelines for selecting external components.

SETTING THE OUTPUT VOLTAGE

The output voltage is set using the feedback pin and a resistor divider connected to the output as shown on the front page schematic. The feedback pin voltage is 0.762V, so the ratio of the feedback resistors sets the output voltage according to the following equation: $V_{OUT}=0.765V(1+(R1/R2))$ Typically R2 will be given as 100Ω -10 k Ω for a starting value. To solve for R1 given R2 and V_{OUT} use R1=R2(($V_{OUT}/0.765V)$ -1).

INPUT CAPACITOR

A low ESR ceramic capacitor (C_{IN}) is needed between the V_{IN} pin and GND pin. This capacitor prevents large voltage transients from appearing at the input. Use a 2.2 µF-10 µF value with X5R or X7R dielectric. Depending on construction, a ceramic capacitor's value can decrease up to 50% of its nominal value when rated voltage is applied. Consult with the capacitor manufacturer's data sheet for information on capacitor derating over voltage and temperature.

INDUCTOR SELECTION

The most critical parameters for the inductor are the inductance, peak current, and the DC resistance. The inductance is related to the peak-to-peak inductor ripple current, the input and the output voltages.

$$L = \frac{(V_{IN} - V_{OUT})V_{OUT}}{V_{IN} \times I_{RIPPLE} \times f_{SW}}$$

A higher value of ripple current reduces inductance, but increases the conductance loss, core loss, and current stress for the inductor and switch devices. It also requires a bigger output capacitor for the same output voltage ripple requirement. A reasonable value is setting the ripple current to be 30% of the DC output current. Since the ripple current increases with the input voltage, the maximum input voltage is always used to determine the inductance. The DC resistance of the inductor is a key parameter for the efficiency. Lower DC resistance is available with a bigger winding area. A good tradeoff between the efficiency and the core size is letting the inductor copper loss equal 2% of the output power. See AN-1197 for more information on selecting inductors. A good starting point for most applications is a 10 µH to 22 µH with 1.1A or greater current rating for the LM2842 or a 0.7A or greater current rating for the LM2840/41. Using such a rating will enable the LM2840/1/2 to current limit without saturating the inductor. This is preferable to the LM2840/1/2 going into thermal shutdown mode and the possibility of damaging the inductor if the output is shorted to around or other longterm overload.

OUTPUT CAPACITOR

The selection of C_{OUT} is driven by the maximum allowable output voltage ripple. The output ripple in the constant frequency, PWM mode is approximated by: $V_{\text{RIPPLE}} = I_{\text{RIPPLE}}$ (ESR+(1/(8f_{SW}C_{OUT}))) The ESR term usually plays the dominant role in determining the voltage ripple. Low ESR ceramic capacitors are recommended. Capacitors in the range of 22 μ F-100 μ F are a good starting point with an ESR of 0.1 Ω or less.

BOOTSTRAP CAPACITOR

A 0.15 μ F ceramic capacitor or larger is recommended for the bootstrap capacitor (C_{BOOT}). For applications where the input voltage is less than twice the output voltage a larger capacitor is recommended, generally 0.15 μ F to 1 μ F to ensure plenty of gate drive for the internal switches and a consistently low R_{DSON}.

SOFT-START COMPONENTS

The LM2840/1/2 has circuitry that is used in conjunction with the \overline{SHDN} pin to limit the inrush current on start-up of the DC/ DC switching regulator. The \overline{SHDN} pin in conjunction with a RC filter is used to tailor the soft-start for a specific application. When a voltage applied to the \overline{SHDN} pin is between 0V and up to 2.3V it will cause the cycle by cycle current limit in the power stage to be modulated for minimum current limit at 0V up to the rated current limit at 2.3V. Thus controlling the output rise time and inrush current at startup. The resistor value should be selected so the current sourced into the \overline{SHDN} pin will be greater then the leakage current of the \overline{SHDN} pin (1.5 μ A) when the voltage at \overline{SHDN} is equal or greater then 2.3V.

SHUTDOWN OPERATION

The SHDN pin of the LM2840/1/2 is designed so that it may be controlled using 2.3V or higher logic signals. If the shutdown function is not to be used the SHDN pin may be tied to V_{IN} . The maximum voltage to the SHDN pin should not exceed 42V. If the use of a higher voltage is desired due to system or other constraints it may be used, however a 100 k Ω or larger resistor is recommended between the applied voltage and the SHDN pin to protect the device.

SCHOTTKY DIODE

The breakdown voltage rating of the diode (D1) is preferred to be 25% higher than the maximum input voltage. The current rating for the diode should be equal to the maximum output current for best reliability in most applications. In cases where the input voltage is much greater than the output voltage the average diode current is lower. In this case it is possible to use a diode with a lower average current rating, approximately $(1-D)I_{OUT}$, however the peak current rating should be higher than the maximum load current. A 0.5A to 1A rated diode is a good starting point.

LAYOUT CONSIDERATIONS

To reduce problems with conducted noise pick up, the around side of the feedback network should be connected directly to the GND pin with its own connection. The feedback network. resistors R1 and R2, should be kept close to the FB pin, and away from the inductor to minimize coupling noise into the feedback pin. The input bypass capacitor C_{IN} must be placed close to the V_{IN} pin. This will reduce copper trace resistance which effects input voltage ripple of the IC. The inductor L1 should be placed close to the SW pin to reduce magnetic and electrostatic noise. The output capacitor, \mathbf{C}_{OUT} should be placed close to the junction of L1 and the diode D1. The L1, D1, and COUT trace should be as short as possible to reduce conducted and radiated noise and increase overall efficiency. The ground connection for the diode, C_{IN} , and C_{OUT} should be as small as possible and tied to the system ground plane in only one spot (preferably at the C_{OUT} ground point) to minimize conducted noise in the system ground plane. For more detail on switching power supply layout considerations see Application Note AN-1149: Layout Guidelines for Switching Power Supplies.

Application Information

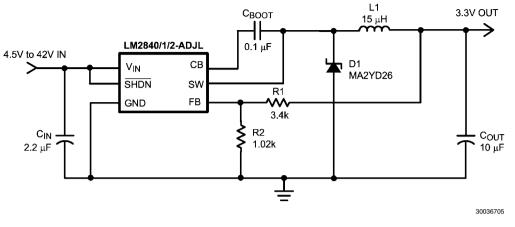


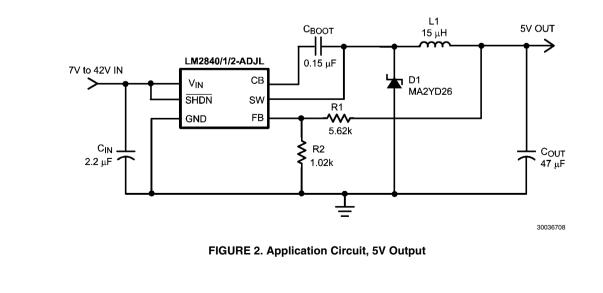
FIGURE 1. Application Circuit, 3.3V Output @ 100 mA

Some Recommended Inductors (Others May Be Used)

Manufacturer	Inductor	Contact Information	
Coilcraft	LPS4018, DO1608C, DO3308, and LPO2506 series	www.coilcraft.com 800-3222645	
MuRata	LQH55D and LQH66S series	www.murata.com	
Coiltronics	MP2 and MP2A series	www.cooperbussman.com	

Some Recommended Input And Output Capacitors (Others May Be Used)

Manufacturer	Capacitor	Contact Information	
Vishay Sprague	293D, 592D, and 595D series tantalum	www.vishay.com 407-324-4140	
Taiyo Yuden	High capacitance MLCC ceramic	www.t-yuden.com 408-573-4150	
Cornell Dubilier	ESRD seriec Polymer Aluminum Electrolytic SPV and AFK series V-chip series	www.cde.com	
MuRata	High capacitance MLCC ceramic	www.murata.com	



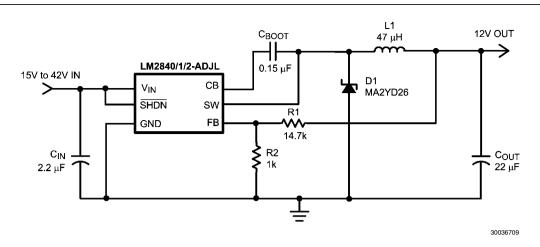


FIGURE 3. Application Circuit, 12V Output

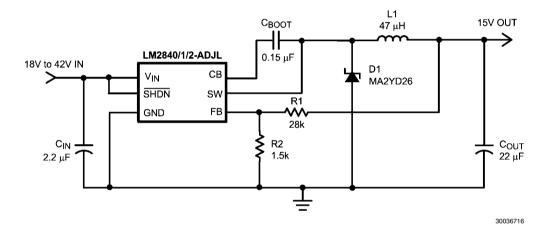
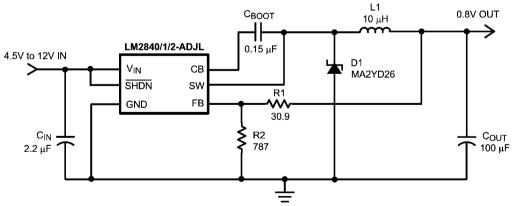


FIGURE 4. Application Circuit, 15V Output



30036717

FIGURE 5. Application Circuit, 0.8V Output

Physical Dimensions inches (millimeters) unless otherwise noted 8 97±0.1 (4X 0.95) (6X 0,69) A (3.6) (1 6) 2.85 SYMM ¢_ 1.65±0.1 (6 X 1) 1.43 зүмм ф RECOMMENDED LAND PATTERN PIN 1 INDEX AREA R0.10-0.25 TYP RO.1 MIN TYP (0.87) 0.12-0.20 TYP MAX 0.25 C 0°-8° TYP 0.1 C Ā -SEATING PLANE 0.05+0.05 4X 0.95 -GAGE PLANE 0.4±0.1 TYP 6X 0.4±0.075 ⊕ 0.200 C AS BS (0.6)

DIMENSIONS ARE IN MILLIMETERS

MK06A (Rev E)

TSOT 6 Pin Package (MK) For Ordering, Refer to Ordering Information Table NS Package Number MK06A

LM2840/LM2841/LM2842/LM2840Q/LM2841Q/LM2842Q

Notes

Notes

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Data Converters	www.national.com/adc	Samples	www.national.com/samples	
Interface	www.national.com/interface	Eval Boards	www.national.com/evalboards	
LVDS	www.national.com/lvds	Packaging	www.national.com/packaging	
Power Management	www.national.com/power	Green Compliance	www.national.com/quality/green	
Switching Regulators	www.national.com/switchers	Distributors	www.national.com/contacts	
LDOs	www.national.com/ldo	Quality and Reliability	www.national.com/quality	
LED Lighting	www.national.com/led	Feedback/Support	www.national.com/feedback	
Voltage References	www.national.com/vref	Design Made Easy	www.national.com/easy	
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